



# CER1055A - PRELIMINARY Band 12 Femto-Cell Duplexer

#### **Features**

- Low Loss with High Rejection
- Superior power handling and reliability

#### **Applications**

 Wireless Infrastructure applications including highperformance carrier-grade femto-cells.



## Description

Surface mount ceramic duplexer supports a universal footprint across all FDD frequency bands enabling the use of a common system PCB. Provides superior rejection, insertion loss, reliability, as well as both peak and average power handling compared to other duplexer technologies.

### **Electrical Specifications**

Parameter	Frequency (MHz)	Typical at 25°C	Spec. at 25°C	Spec. over -40°C to +85°C
Nominal Impedance	-	50 ohms	-	-
Average Input Power	-	-	-	3.0 Watt max
Peak Input Power	-	-	-	20 Watt max
Antenna to UL Response				
Passband Insertion Loss (5 MHz avg)	699-715	2.3 dB	2.6 dB max	2.8 dB max
Passband Return Loss	699-715	14 dB	11 dB min	11 dB min
Attenuation:	729-745	43 dB	40 dB min	38 dB min
	652	25 dB	16 dB min	16 dB min
DL to Antenna Response				
Passband Insertion Loss (5 MHz avg)	729-745	2.3 dB	2.6 dB max	2.8 dB max
Passband Return Loss	729-745	14 dB	11 dB min	11 dB min
Attenuation:	699-715	47 dB	44 dB min	42 dB min
	777	18 dB	16 dB min	16 dB min
DL to UL Response				
Attenuation for UL band	699-715	49 dB	45 dB min	43 dB min
Attenuation for DL band	729-745	45 dB	42 dB min	40 dB min

Note: CTS tests each unit to the critical specifications above. Subsequent audits may deviate due to repeatability among different test systems which shall not exceed these allowances.

Specification Allowance
Insertion Loss 0.1 dB
Return Loss 1.0 dB
Attenuation 1.0 dB

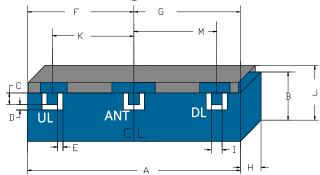
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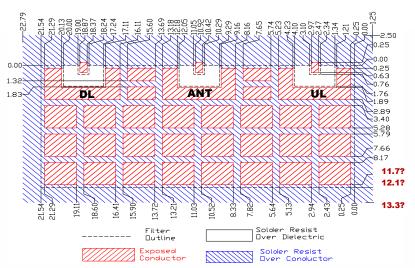
## PRELIMINARY - CER1055A

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## **Mechanical Drawing**



## **PCB Layout**



Dim.	Nominal (mm)	Tolerance (±mm or Max)	
Α	2154	Max	
В	11.10?	Max	
С	0.76	0.13	
D	1.00	0.13	
Е	1.00	0.13	
F	10.67	0.13	
G	10.67	0.13	
Н	4.00	Max	
-	0.76	0.13	
J	12.10?	Max	
K	7.95	0.13	
М	7.95	0.13	

IMPORTANT: Please assure >=20mils (0.5mm) thickness of dielectric beneath the I/O Pads <u>and</u> the surrounding clearance zone down to the required ground plane.

Please assure sufficient ground vias between the top metal ground plane and the primary ground plane.

Recommended solder: 6 mils of SAC305 with reflow including 120s of soak at 217°C, and up to 30 sec peak at 241°C.

## Packaging and Marking

Dimensio	on Unit	s Spec.	- Prod <u>uc</u>	t Marking		
Reel Diame	eter mm	330	_	CTS		
Reel Weig	ht kg	5.9		055		
Reel Quant	tity ea.	500	Υ	WW		
000	Customer F	eed Direction	$ \begin{array}{c} \uparrow \\ \hline \downarrow \\ \downarrow \\ \hline $	Bo MM/(Incl		
Ш			MM/(Inches)	- Ko		
Po — MM/(Inches)	-			MM/(Inches)		
AO MM/(Inches)						
Wo	Ao	Bo	Ko	Po		
2.260 in	0.457 in	0.860 in	0.169 in	0.629 in		
32.0 mm	11.6 mm	21.85 mm	4.3 mm	16.0 mm		

## Electrical Response

